

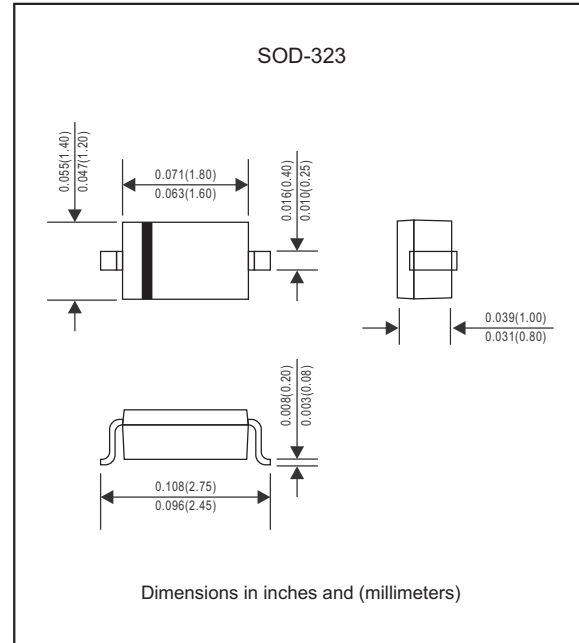
### Features

- Low current rectification and high speed switching.
- Small surface mount type.
- Up to 70mA current capability.
- Low forward voltage drop ( $V_F = 1.00V$  typ. @15mA)
- Silicon epitaxial planar chip, metal silicon junction.
- Lead-free parts for green partner, exceeds environmental standards of MIL-STD-19500 /228
- High speed ( $t_{rr} < 5$  ns)
- Compliant to Halogen - free

### Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-323
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any

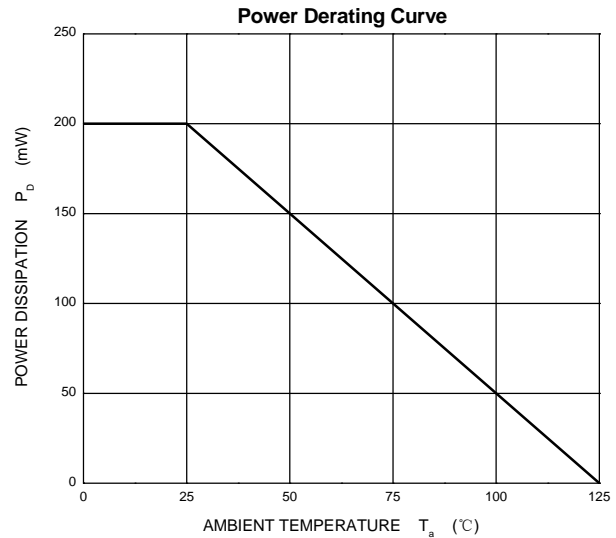
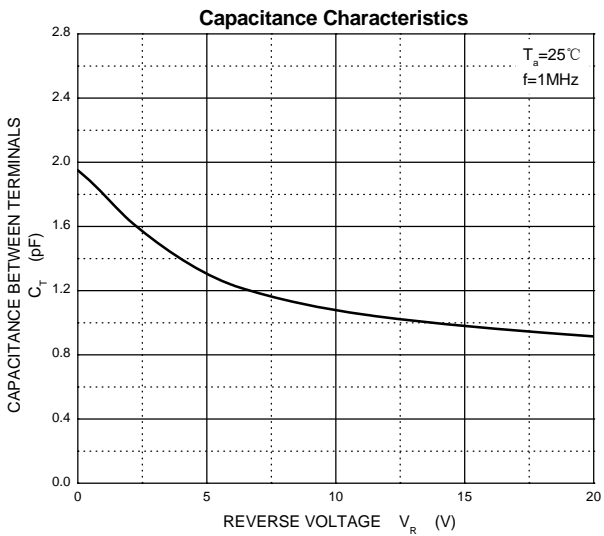
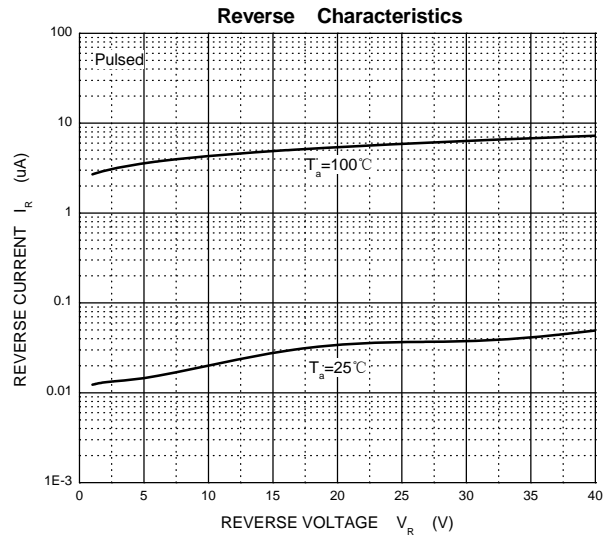
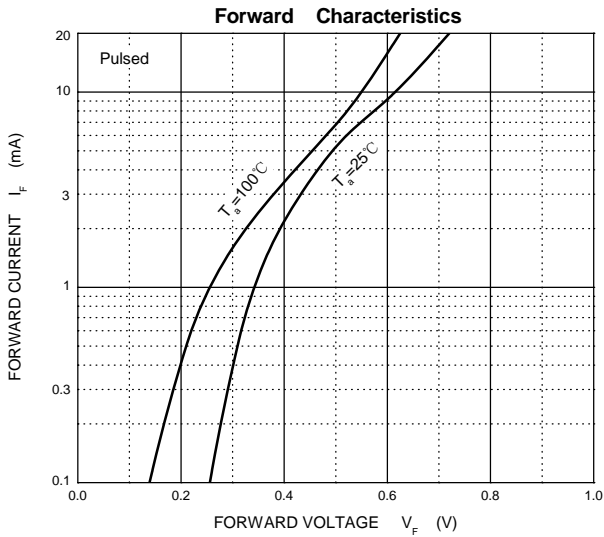
### Package outline





### Maximum ratings and Electrical Characteristics (AT $T_A=25^\circ C$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Repetitive peak reverse voltage		$V_{RRM}$			70	V
Reverse voltage		$V_R$			70	V
Repetitive peak forward current	@ $t < 1.0s$	$I_{FSM}$			100	mA
Forward current		$I_F$			70	mA
Power Dissipation		$P_D$			200	mW
Thermal Resistance	Junction to Ambient	$R_{\theta JA}$			625	$^\circ C/W$
Junction temperature		$T_J$	-55		+125	$^\circ C$
Storage temperature		$T_{STG}$	-65		+125	$^\circ C$
Forward voltage	$I_F = 1.0$ mA	$V_F$			0.41	V
	$I_F = 15$ mA	$V_F$			1.00	V
Reverse current	$V_R = 50$ V	$I_R$			100	nA
Diode capacitance	$V_R = 0$ V, $f = 1$ MHz	$C_D$			2	pF
Reverse recovery time	$I_F = 10$ mA, $V_R = 10$ mA, $I_{RR} = 0.1 \times I_R$ , $RL=100\Omega$	$t_{rr}$			5	ns

### Typical Characteristics



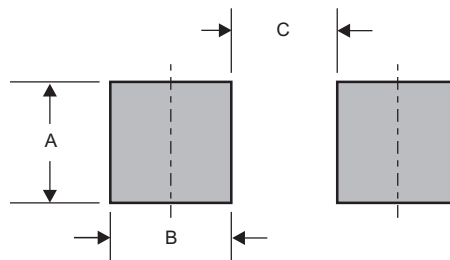
### Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

### Marking

Type number	Marking code
BAS70WS	K73

### Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-323	0.033 (0.83)	0.025 (0.63)	0.063 (1.60)